# Switching (60V, 200mA)

# **RHU002N06**

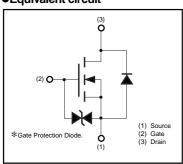
#### Features

- 1) Low on-resistance.
- 2) High ESD.
- 3) High-speed switching.
- 4) Low-voltage drive (4V).
- 5) Easily designed drive circuits.
- 6) Easy to use in parallel.

#### ●Structure

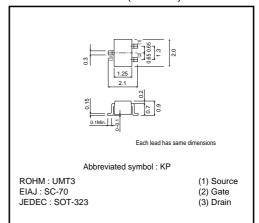
Silicon N-channel MOSFET transistor

#### Equivalent circuit



\* A protection diode has been built in between the gate and the source to protect against static electricity when the product is in use. Use the protection circuit when fixed voltages are

# ●External dimensions (Unit: mm)



#### ● Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit
Drain-source voltage		Voss	60	V
Gate-source voltage		Vgss	±20	V
Drain current	Continuous	ΙD	200	mA
	Pulsed	IDP *1	800	mA
Source current	Continuous	Is	200	mA
	Pulsed	Isp*1	800	mA
Total power dissipation		P <sub>D</sub> *2	200	mW
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55 to +150	°C

<sup>\*1</sup> Pw≤10μs, Duty cycle≤1% \*2 Each terminal mounted on a recommended

#### ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Conditions	
Gate leakage current	Igss	-	-	±10	μΑ	Vgs=±20V, Vps=0V	
Drain-source breakdown voltage	V (BR) DSS	60	-	_	V	I <sub>D</sub> =10μA, V <sub>G</sub> s=0V	
Drain cutoff current	IDSS	_	_	1	μΑ	Vps=60V, Vgs=0V	
Gate threshold voltage	VGS (th)	1	-	2.5	V	Vps=10V, Ip=1mA	
5	RDS (on)*1	_	1.7	2.4	Ω	In=200mA, Vgs=10V	
Drain-source on-state resistance		_	2.8	4.0		In=200mA, Vgs=4V	
Forward transfer admittance	I Yfs I*1	100	_	_	mS	V <sub>DS</sub> =10V, I <sub>D</sub> =200mA	
Input capacitance	Ciss	_	15	_	pF	V <sub>DS</sub> =10V V <sub>GS</sub> =0V f=1MHz	
Output capacitance	Coss	_	8	-	pF		
Reverse transfer capacitance	Crss	_	4	_	pF		
Turn-on delay time	<b>t</b> d (on)*2	_	6	-	ns	I <sub>D</sub> =100mA, V <sub>DD</sub> =30V V <sub>GS</sub> =10V R <sub>L</sub> =300Ω R <sub>GS</sub> =10Ω	
Rise time	tr*2	_	5	_	ns		
Turn-off delay time	td (off)*2	_	12	-	ns		
Fall time	t <sub>f</sub> *2	-	95	-	ns		
Total gate charge	Qg*2	_	2.2	4.4	nC	V <sub>DD</sub> ≒30V	
Gate-source charge	Q <sub>gs</sub> *2	_	0.6	_	nC	V <sub>GS</sub> =10V I <sub>D</sub> =200mA	
Gate-drain charge	Q <sub>gd</sub> *2	_	0.3	_	nC		

<sup>\*1</sup> Pw≤300μs, Duty cycle≤1% \*2 Pulsed

## Packaging specifications

	Package	Taping
	Code	T106
Туре	Basic ordering unit (pieces)	3000
RHU002N06	0	

## •Electrical characteristic curves

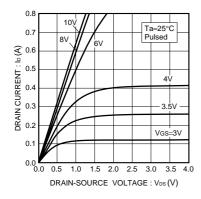


Fig.1 Typical Output Characteristics

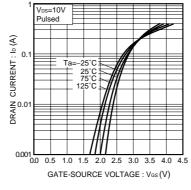


Fig.2 Typical Transfer Characteristics

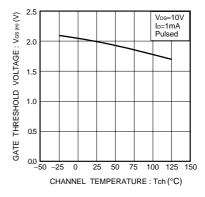


Fig.3 Gate Threshold Voltage vs. Channel Temperature

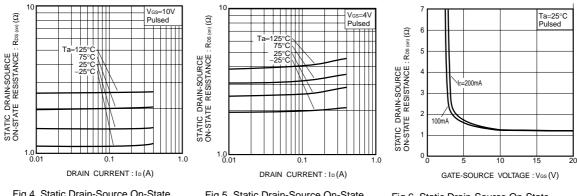


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current ( I )

Fig.5 Static Drain-Source On-State Resistance vs. Drain Current ( II )

Fig.6 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

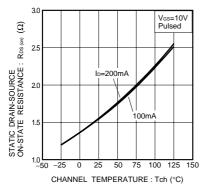


Fig.7 Static Drain-Source On-State
Resistance vs. Channel Temperature

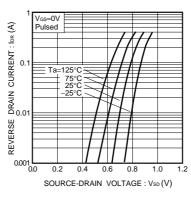


Fig.8 Reverse Drain Current vs. Source-Drain Voltage ( I )

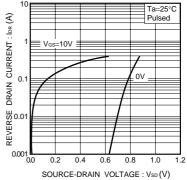


Fig.9 Reverse Drain Current vs. Source-Drain Voltage ( II )

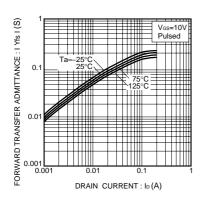


Fig.10 Forward Transfer Admittance vs. Drain Current

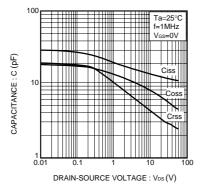


Fig.11 Typical Capacitance vs. Drain-Source Voltage

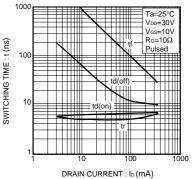


Fig.12 Switching Characteristics

# •Switching characteristics measurement circuit

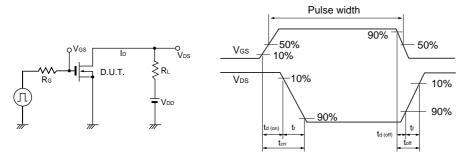


Fig.13 Switching time test circuit

Fig.14 Switching time waveforms

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